

IRPS 2017

April 2-6, 2017

Hyatt Regency, Monterey CA

Abstract Submission Instructions

General Guidance

- Abstracts must be no longer than 2 pages.
 - Typically 1 page of text and 1 page of figures.
 - See the sample abstract on the IRPS web-site abstract submission page:
<http://irps.org/irps-call-for-papers/abstract-submission/>
- Deadline for abstract submission is **October 15, 2016**
 - Uploaded abstracts and other information may be modified up until this date.
 - To modify existing uploads, keep the passcode information the site assigned to your first upload.
- Late Paper deadline is **January 6, 2017**
 - Late papers must be camera-ready manuscripts, not abstracts.

Submission Web-Site:

<https://www.softconf.com/h/irps2017/>

Start the submission process by clicking here



The 2017 IEEE International Reliability Physics Symposium

IRPS 2017

Monterey, CA, USA
April 2-6, 2017

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- Click [HERE](#) to make a *new* submission.
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The 2017 IEEE International Reliability Physics Symposium

IRPS 2017

Submission Page

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See the next page for additional details.

Abstract Submission Categories

- Pick the most appropriate category into which your abstract fits.
- Categories from the Call For Papers are shown below.

Circuits and Products and Systems

Circuit Reliability – Includes digital, mixed-signal, and RF applications; design for reliability

Circuit Aging Simulation – Includes compact modeling; statistical methods

Product IC Reliability – Includes burn-in; defect detection; on-chip sensors; modeling

Consumer Electronics Reliability – Includes smart phones; wearable devices; tablets; health devices

Reliability Testing – Includes reliability equipment, tools, and test methods

Electronic System Reliability – Includes automotive, space, communications, medical, energy, and photovoltaic applications; screening techniques; system monitoring; failure root cause determination; modeling methodologies

Soft Errors – Includes neutron and alpha particle SER; multi-bit SER/SEU; mitigation techniques; simulation

ESD and Latchup – Includes component and system-level ESD design; modeling and simulation

3D Assembly – Includes multichip modules; 3D integration with TSV; thermomechanical stress; wafer thinning effects

Packaging – Includes chip-package interaction; fatigue; power dissipation issues

Device, Process, and Materials

Transistors – Includes hot carrier phenomena; bias-temperature instability; random telegraph noise; advanced transistor scaling challenges; Ge and III-V channels

Gate Dielectrics – Includes TDDB modeling; reliability of novel gate dielectrics; modeling of progressive breakdown; gate dielectric reliability for III-V FETs

Beyond CMOS Devices – Includes reliability of tunnel FETs, transistors with 2D semiconductor (graphene, MoS₂), and spintronics

Wide Band-Gap – Includes reliability of wide bandgap (GaN, SiC) power devices

Back-End Reliability – Includes Electromigration; Joule heating; stress migration; low-k dielectric breakdown; middle of the line processes

Process Integration – Includes new process related reliability issues; foundry reliability challenges

Failure Analysis – Includes evidence of new failure mechanisms; advances in failure analysis techniques

Memory – Includes DRAM and NVM; failure mechanisms in novel memory devices including 3D Flash and ReRAM

Photovoltaic Devices – Includes reliability of solar cell devices in silicon, CdTe, CIGS, etc.

MEMS – Reliability of New Structures. Sensors. Actuators. Reliability Testing. Analysis & Modeling

Final Information

Summary: (*)

Type (or cut-and-paste) a short plain text summary for your submission. It should not include the author/title information, which was already entered above.

Provide a 50 – 75 word summary of your work.
This could be what is used as the *Abstract*
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We would like to use this material to highlight
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Abstract Submission - 2 page maximum

Only PDF files are accepted. The two-page abstract must be submitted. The file's name should have the proper MIME extent associated with its document type. For example, a pdf file should have a name such as "mypaper.pdf".

Find the file for your submission:

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Additional Questions?

- If you have additional questions, please contact one of us:
- Technical content / formatting questions:
 - Mark Porter, TPC (mark.porter@medtronic.com)
 - Christine Hau-Riege, Vice-TPC (chaurieg@qti.qualcomm.com)
- SoftConf web-site or administrative questions:
 - Phyllis Mahoney, Widerkehr (phyllism@widerkehr.com)